Press Release

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Quik-Pak Acquires Flip Chip Assembly, Radiation Sensor and Laser Micromachining Business Units of Aguila Technologies

San Diego, CA, September 25, 2008 - Quik-Pak, a division of Delphon Industries, announced today the acquisition of Aguila Technologies' flip chip assembly, detector array processing, and laser micromachining business units. The acquisition is part of Quik-Pak's ongoing effort to expand its advanced packaging and assembly services.

The acquisition, which includes key technical personnel and proprietary equipment, enables Quik-Pak to provide a full turnkey solution that supports wafer backgrinding and dicing, the latest packaging technologies and advanced assembly services. "The new acquisition coupled with Quik-Pak's current services will enable us to more completely meet the increasing demands of our customers and facilitate faster time-to-market

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for their new products,” says Steve Swendrowski, General Manager.

About Quik-Pak:

The company specializes in open-cavity plastic packages and assembly in 24 hours or less. A limitless array of open-cavity packages are available with no minimum quantity and can be provided as part of a turnkey assembly solution along with backgrinding, wafer dicing, die/wire bonding, laser micromachining, detector array processing, remolding and marking/branding. Custom assembly services are also offered for ceramic packages, chip-on-board, stacked die, MEMS, etc. Quik-Pak's unique offerings deliver faster time to market and reduced prototype costs for new devices, while providing excellent flexibility, quality and customer service.

For further information:

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